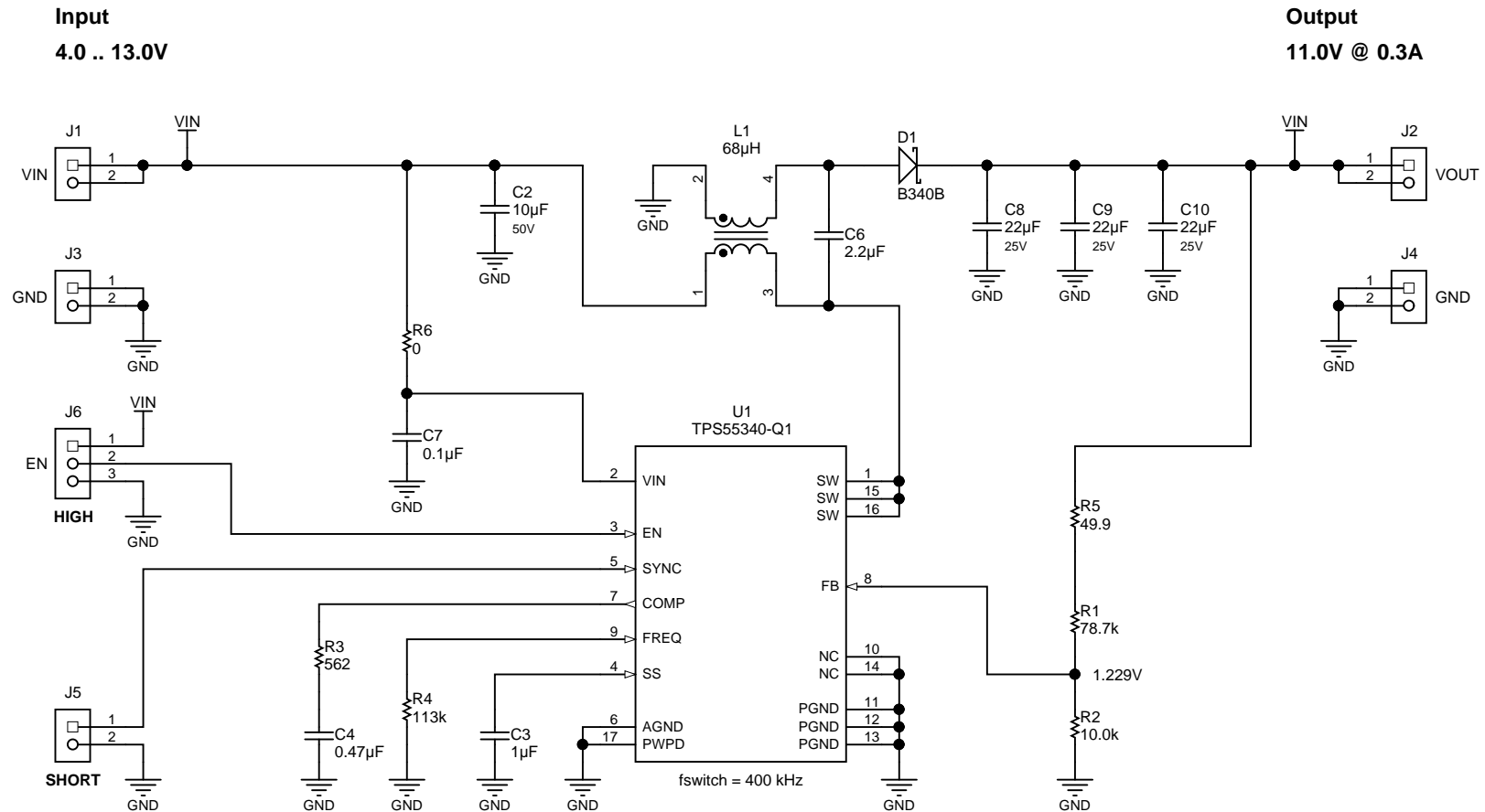


Revision History	
Revision	Notes
A	* Paper Design
B	* Built & Tested



Design Notes

- * Modified TPS55340EVM-147
- * R5 for test purpose only

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Orderable: EVM_orderable	Designed for: Public Release	Mod. Date: 9/19/2017
TID #: TID	Project Title: Automotive Sepic	
Number: PMP30342	Rev: B	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 1 of 1
Drawn By:	File: PMP30342RevB.SchDoc	Size: A4
Engineer: Matthias Ulmann	Contact: http://www.ti.com/support	



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